

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A metal laminate comprising a metal layer having a metal oxide layer film laminated to an insulating layer, where the insulating layer is subjected to an etching processing to form a pattern, wherein, in a surface of the metal layer which is in contact with the insulating layer, respective concentrations of main metal element and oxygen element constituting the metal layer are measured from the surface of the metal layer towards the inside of the metal layer in a time-elapsing manner according to AES (Auger electron spectroscopy) and the thickness of a metal oxide film of the surface of the metal layer measured at a depth where atomic concentrations of the main metal element and the oxygen element constituting the metal layer are equal to each other is at least 25Å and less than 50Å.

2. (Currently Amended) The metal laminate according to claim 1, wherein the ~~metal layer includes at least one element~~ main metal element is selected from the group consisting of iron element, copper element, aluminum element, nickel element and molybdenum element.

3. (Previously Presented) The metal laminate according to claim 1, wherein the insulating layer is a resin selected from the group consisting of polyimide, polyamide, polyamideimide.

4. (Currently Amended) The metal laminate according to claim 1, wherein the metal laminate is a double-sided metal laminate comprising a SUS layer/a polyimide layer/a metal layer selected from the group consisting of copper, SUS and copper alloy, both of said SUS layer and said metal layer having the metal oxide film, and wherein both the respective concentrations of the iron and oxygen in the SUS layer and the main metal and oxygen of the metal layer are measured according to AES and the depths where atomic concentrations of the iron and the oxygen of the SUS layer and the main metal and oxygen of the metal layer are equal to each other are both less than 50Å.

5. (Previously Presented) The metal laminate according to claim 4, wherein the polyimide layer comprises a thermoplastic polyimide layer, a non-thermoplastic polyimide layer and a thermoplastic polyimide layer in this order.

6. (Previously Presented) A flexure for a suspension for a hard disc, manufactured from a metal laminate according to claim 5 wherein the metal laminate comprises the etched insulating layer.

7. (Canceled)

8. (Previously Presented) A plasma etching method comprising etching a metal laminate according to claim 5.

9. (Previously Presented) A wet etching method comprising etching a metal laminate according to claim 5 with alkaline aqueous solution.

10. (Previously Presented) A flexure for a suspension for a hard disc, manufactured from a metal laminate according to claim 4 wherein the metal laminate comprises the etched insulating layer.

11. (Previously Presented) A flexure for a suspension for a hard disc, manufactured from a metal laminate according to claim 3 wherein the metal laminate comprises the etched insulating layer.

12. (Previously Presented) A flexure for a suspension for a hard disc, manufactured from a metal laminate according to claim 2 wherein the metal laminate comprises the etched insulating layer.

13. (Previously Presented) A flexure for a suspension for a hard disc, manufactured from a metal laminate according to claim 1 wherein the metal laminate comprises the etched insulating layer.

14. (Previously Presented) A plasma etching method comprising etching a metal laminate according to claim 4.

15. (Previously Presented) A plasma etching method comprising etching a metal laminate according to claim 3.

16. (Previously Presented) A plasma etching method comprising etching a metal laminate according to claim 2.

17. (Previously Presented) A plasma etching method comprising etching a metal laminate according to claim 1.

18. (Previously Presented) A wet etching method comprising etching a metal laminate according to claim 4 with alkaline aqueous solution.

19. (Previously Presented) A wet etching method comprising etching a metal laminate according to claim 3 with alkaline aqueous solution.

20. (Previously Presented) A wet etching method comprising etching a metal laminate according to claim 2 with alkaline aqueous solution.

21. (Previously Presented) A wet etching method comprising etching a metal laminate according to claim 1 with alkaline aqueous solution.

22. (Currently Amended) A method for manufacturing a metal laminate comprising laminating a metal layer to an insulating layer where the insulating layer is to be subjected to an etching processing, wherein the metal layer is selected so that the surface of the metal layer which is in contact with the insulating layer, has a thickness of a metal oxide film of the surface of the metal layer measured at a depth where atomic concentrations of the main metal element and the oxygen element constituting the metal layer are equal to each other is at least 25 Å and less than 50Å, the respective concentrations of main metal element and oxygen element constituting the metal layer being measured from the surface of the metal layer towards the inside of the metal layer in a time-elapsing manner according to AES (Auger electron spectroscopy).